FIG. 1

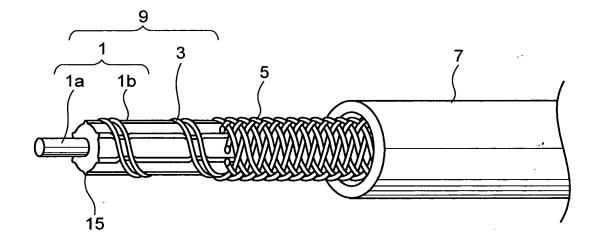


FIG. 2

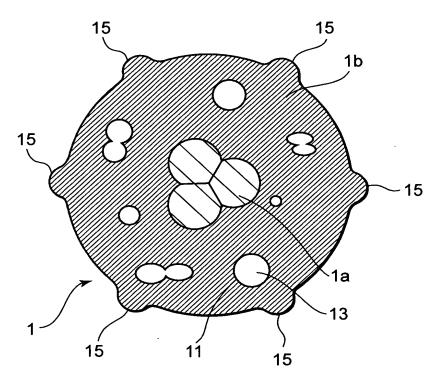


FIG. 3

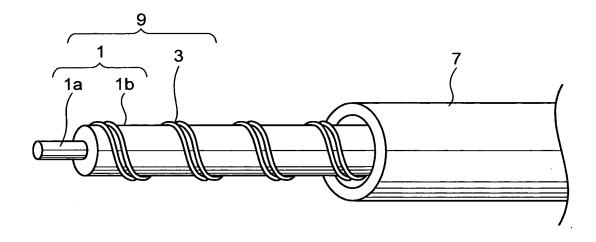
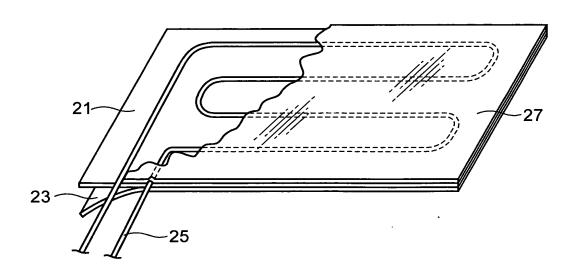


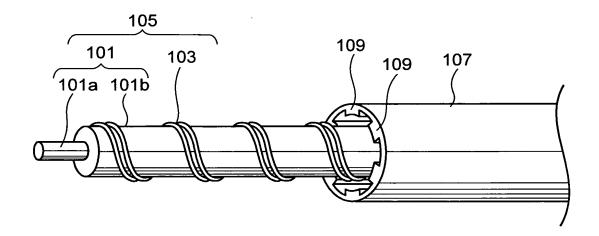
FIG. 4



		EXAMPLE 1	EXAMPLE 2	EXAMPLE 3	EXAMPLE 4	EXAMPLE 5	EXAMPLE 6	COMPARATIVE EXAMPLE 1	COMPARATIVE EXAMPLE 2
	TENSILE RESISTANT MEMBER	GLASS CODE + SILICONE VARNISHING							
ELASTIC CORE	ELASTIC MEMBER	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	100 W/T PARTS OF SILICONE RUBBER + 2 W/T PART OF FOAMING AGENT (AIBN)	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	100 WIT PARTS OF SILICONE RUBBER + 3 WIT PARTS OF POLYACETAL HOMOPOLYMER	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	SILICONE RUBBER NO FOAMING AGENT	SILICONE RUBBER NO FOAMING AGENT
	OUTER	INSCRIBED CIRCLE: 1.6 mm CIRCUMSCRIBED CIRCLE: 1.8 mm (6 RADIAL PROTRUSIONS)							
	CONDUCTOR	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm ¢	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm \$\phi\$	CENTER: FLUX NOT INCLUDED EUTECTIC SOLDER WIRE 0.6 mm $\phi$	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm¢	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm¢	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm¢	CENTER: FLUX NOT INCLUDED EUTECTIC SOLDER WIRE 0.6 mm ф	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm¢
	INSULATING COVER	ETHYLENE COPOLYMER	ETHYLENE COPOLYMER	ETHYLENE COPOLYMER	ETHYLENE COPOLYMER	ETHYLENE PROPYLENE RUBBE	ETHYLENE COPOLYMER	ETHYLENE COPOLYMER	ETHYLENE
ଜ୍ଞ	SPACE LAYER (GLASS BRAID)	YES	YES	YES	YES	YES	ON	YES	YES
Ш	EXPERIMENT 1	183°C	183°C	183℃	183°C	183 ໍC	183°C	183°C	183°C
ŭ	EXPERIMENT 2	310°C	305°C	3200	300,0	310°C	330,0	360°C	345°C

-1G. 5

FIG. 6



## FIG. 7

EXAMPLE 10	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mmø	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER NO INNER PROTRUSION	217°C	370,0
EXAMPLE 9	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	2.2 mm¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER 6 INNER PROTRUSIONS 0.6 × 0.5 mm	217°C	320,0
EXAMPLE 8	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	2.2 mmø	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm $\phi$	ETHYLENE COPOLYMER   ETHYLENE COPOLYMER   ETHYLENE COPOLYMER   ETHYLENE COPOLYMER 6 INNER PROTRUSIONS   6 INNER PROTRUSIONS   0.6 $\times$ 0.3 mm   0.6 $\times$ 0.3 mm	217°C	310°C
EXAMPLE 7	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER 6 INNER PROTRUSIONS 0.6 × 0.3 mm	217°C	340,0
	TENSILE RESISTANT  MEMBER	ELASTIC MEMBER	OUTER DIAMETER	CONDUCTOR	INSULATING COVER	EXPERIMENT 1	EXPERIMENT 2

FIG. 8

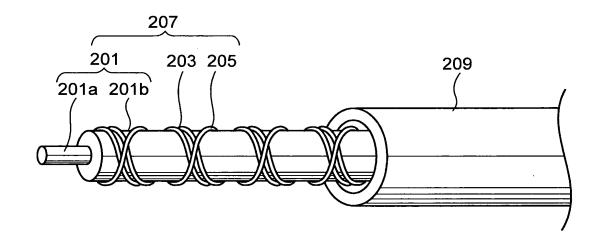


FIG. 9

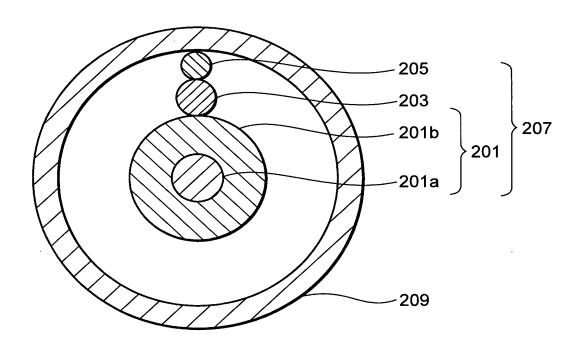


FIG. 10

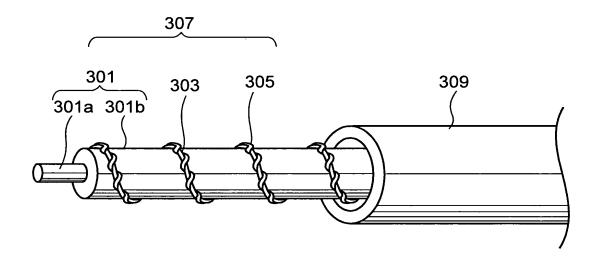


FIG. 11

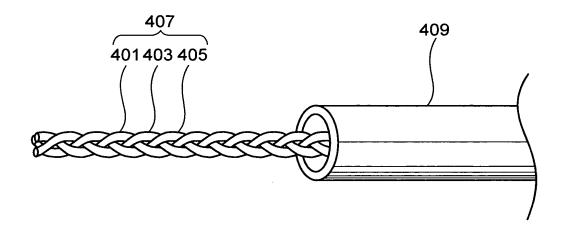
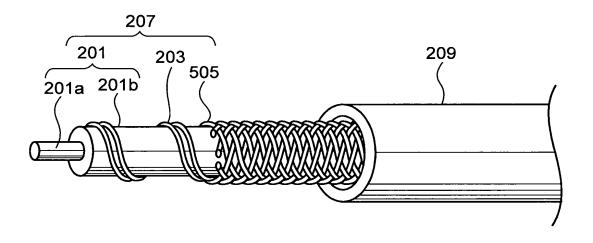


FIG. 12



## FIG. 13

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EXAMPLE 14	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm $\phi$	ETHYLENE COPOLYME	**	217°C	370,0
EXAMPLE 13	ON	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.2 mm¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER ETHYLENE COPOLYMER	POLYPHENYLENE SULFIDE MONOFILAMENT	217°C	350,0
EXAMPLE 12	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm $\phi$	ETHYLENE COPOLYMER	POLYPHENYLENE SULFIDE MONOFILAMENT	217°C	310°C
EXAMPLE 11	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm ¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm $\phi$	ETHYLENE COPOLYMER	POLYPHENYLENE SULFIDE MONOFILAMENT	217°C	330,0
	TENSILE RESISTANT MEMBER	MEMBER MEMBER	OUTER DIAMETER	CONDUCTOR	INSULATING COVER	LINE-SHAPED INSULATOR	EXPERIMENT 1	EXPERIMENT 2
L	LINGOLATI	ING COKE MEME	L	L	L	Щ		

FIG. 14

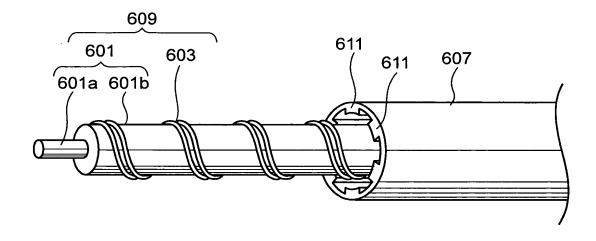
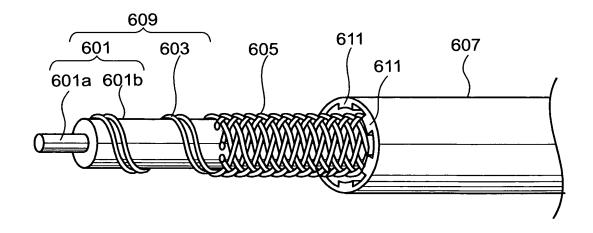


FIG. 15



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EXAMPLE 18.	GLASS CODE + SILICONE - VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm ф	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER + EP RUBBER (CONTRACTED) 6 INNER PROTRUSIONS 0.6 × 0.3 mm	YES	217°C	320 °C	72 hr	4 hr	2 hr
EXAMPLE 17	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm ¢	CENTER: FLUX INCLUDED EUTECTIC SOLDER WIRE 0.6 mm $\phi$	ETHYLENE COPOLYMER + EP RUBBER (CONTRACTED) 6 INNER PROTRUSIONS 0.6 × 0.3 mm	ON	183°C	320°C	72 hr	4 hr	2 hr
EXAMPLE 16	GLASS CODE + SILICONE VARNISHING	SILICONE RUBBER NO FOAMING AGENT	1.8 mm ø	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm ¢	ETHYLENE COPOLYMER + EP RUBBER (CONTRACTED) 6 INNER PROTRUSIONS 0.6 × 0.3 mm	NO	217°C	370°C	72 hr	4 hr	2 hr
EXAMPLE 15	GLASS CODE + SILICONE VARNISHING	100 W/T PARTS OF SILICONE RUBBER + 1 W/T PART OF FOAMING AGENT (AIBN)	1.8 mm ¢	CENTER: FLUX INCLUDED NON-LEAD SOLDER WIRE 0.5 mm $\phi$	ETHYLENE COPOLYMER + EP RUBBER (CONTRACTED) 6 INNER PROTRUSIONS 0.6 × 0.3 mm	ON	217°C	320°C	72 hr	4 hr	2 hr
	TENSILE RESISTANT	ELASTIC	OUTER	CONDUCTOR	INSULATING COVER	SPACE LAYER(GLASS BRAID)	EXPERIMENT 1	EXPERIMENT 2	260°C	5 280°C	300,0
		NG CORE MEM	BER		<b>=</b>	SPA(	·			EXP.	3

FIG. 16